

## CLAIMS

1. A cooling device for an electronic equipment, comprising:

a first cooling panel (1) wherein a first passage (11) through which refrigerant circulates is formed;

a second cooling panel (2) wherein a second passage (21) through which said refrigerant circulates is formed, said second cooling panel being disposed to oppose said first cooling panel (1); and

a circulation pump (3) for circulating said refrigerant through said first passage (1) and said second passage (2) to thereby diffuse heat transferred to said first cooling panel (1) and said second cooling panel (2).

2. The cooling device for an electronic equipment according to claim 1, further comprising a coupling member (61, 62) bearing said first cooling panel and said second cooling panel for opening and closing with respect to each other, and said connecting member has a flexibility.

3. The cooling device for an electronic equipment according to claim 1, wherein at least one of said first cooling panel (1) and said second cooling panel (2) includes a micro-channel structure (12) within said passage (11, 21), said micro-channel structure including a plurality of narrow passages having a width smaller than a width of said passage (11, 21).

4. The cooling device for an electronic equipment according to any one of claims 1 to 3, wherein said at least one of said first cooling panel (1) and said second cooling panel (2) includes an area (13A) in which an air-cooled fin (13) is formed on a surface thereof, said area (13A) being  
5 disposed downstream of said micro-channel structure (12).
5. The cooling device for an electronic equipment according to claim 4, wherein said passage in said area (13A) is wobbled.
6. The cooling device for an electronic equipment according to claim 4, wherein a cooling fan (5) is disposed corresponding to said air-cooled fin (13).
7. The cooling device for an electronic equipment according to claim 1, wherein said circulation pump (3) is fixed onto a surface of said second cooling panel (2).
8. The cooling device for an electronic equipment according to claim 1, wherein a reservoir (4) communicated with said second passage (21) is disposed on a surface of said second cooling panel (2).
9. The cooling device for an electronic equipment according to claim 1, wherein a reservoir (411) communicated with said second passage (21) is

formed within said second cooling panel (2).

10. The cooling device for an electronic equipment according to claim 1, wherein at least one of said first cooling panel (1) and said second cooling panel (2) is formed by bonding together a top heat radiation panel (23) and a bottom heat radiation panel (24), in at least one of which is formed a  
5 groove (23).

11. The cooling device for an electronic equipment according to claim 1, wherein said first cooling panel (1) has an area smaller than an area of said second cooling panel (2).

12. The cooling device for an electronic equipment according to claim 1, wherein said first passage (11) has a width smaller than a width of said second passage (21).

13. The cooling device for an electronic equipment according to claim 1, wherein said first passage (11) has a depth larger than a depth of said second passage (21).

14. An electronic equipment mounting thereon the cooling device for electronic equipment according to any one of claims 1 to 12.